



What's Driving *Automotive Electronics Assembly and Packaging*

Date: 14 October 2020 (Wednesday)
Time: 09.30 AM – 11.00 AM (GMT +8)
Platform: CISCO Webex
Registration: <https://bit.ly/3c2Yo3i>



DR ANDY MACKIE
*Principal Engineer & Manager,
Thermal Interface Material Applications
Indium Corporation*





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Agenda:

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| 0915 – 0930 | Welcoming remarks |
| 0930 – 1030 | Industrial Talk by Dr Andy Mackie |
| 1030 – 1100 | Q & A |





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The evolution of the automobile over the past decade has been faster than ever before, and the 2020s promise even more rapid progress. The changes we will all experience include the nature of car ownership, how the car is powered, increased safety, and driver automation. Each of these changes is only possible with advances in electronics hardware and systems, electronics assembly, and semiconductor packaging. Indium Corporation's Dr. Andy Mackie will discuss the impact of these changes on electronics assembly and packaging, and the impact of mission profiles on component and systems level reliability.





Dr Andy Mackie

Principal Engineer & Manager, Thermal Interface Material Applications Indium Corporation

Dr. Mackie is the Principal Engineer and Manager, Thermal Interface Materials Applications. He served as the Senior Product Manager for Indium Corporation's Semiconductor and Advanced Assembly Materials before he took on this new role. He is an electronics industry expert with a technical background in physical chemistry, surface chemistry, rheology, and semiconductor fabrication and assembly materials and processes. Andy's professional experience covers all aspects of electronics manufacturing from wafer fabrication to semiconductor packaging and SMT/electronics assembly. Dr. Mackie also has responsibility for development of Indium Corporation's Applied Technology Roadmap.





Dr. Mackie has been an invited International keynote speaker and has lectured internationally on subjects ranging from sub-ppb metals analysis in supercritical carbon dioxide to solder paste rheology. He holds patents in novel polymers, heterogeneous catalysis, and solder paste formulation.

Dr. Mackie holds a Ph.D. in physical chemistry from the University of Nottingham, UK, and a Master's of Science (MSc) in colloid and interface science from the University of Bristol, UK.

He is an alumnus of the UC Berkeley Product Management program (2015)

